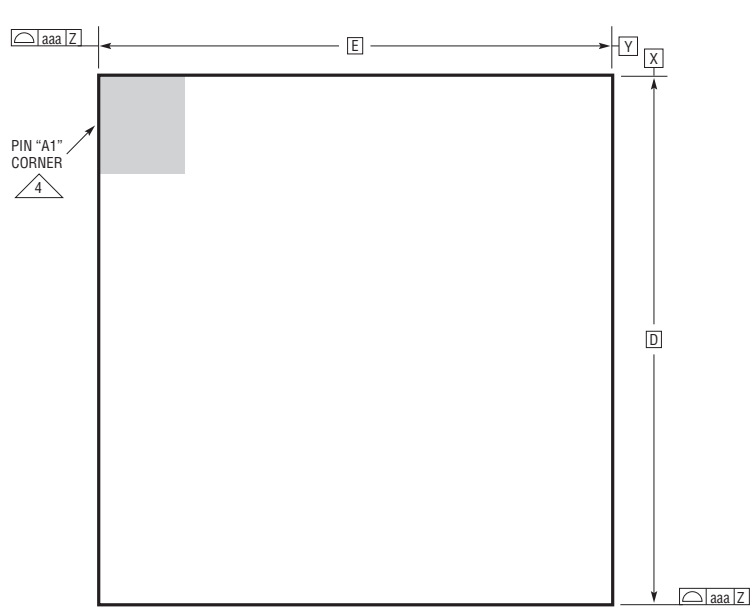
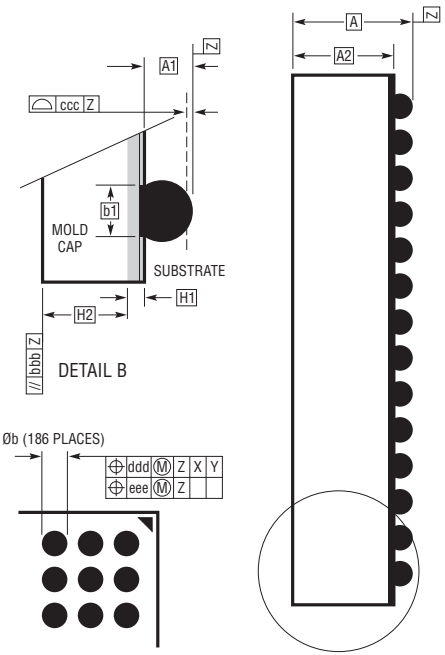


BGA Package
186-Lead (15mm × 15mm × 3.32mm)
 (Reference LTC DWG# 05-08-1670 Rev A)

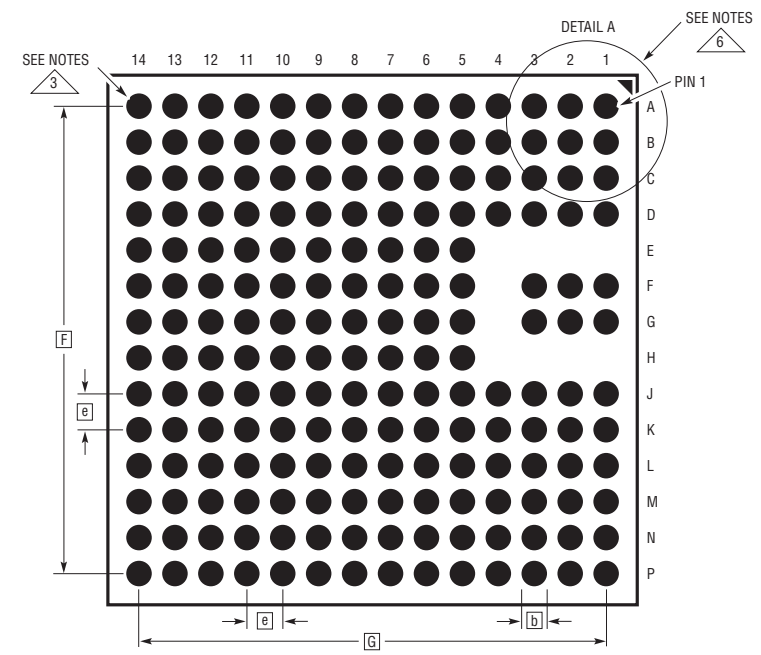


PACKAGE TOP VIEW

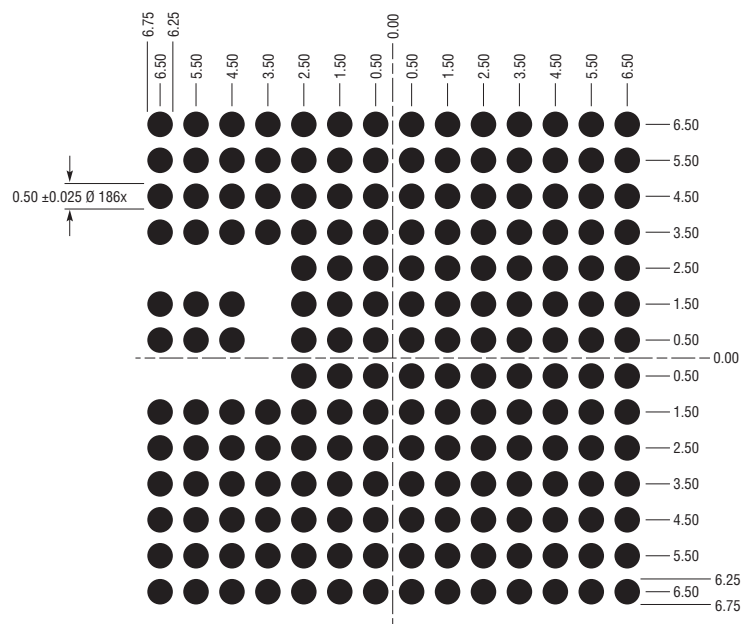


DETAIL A

DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW

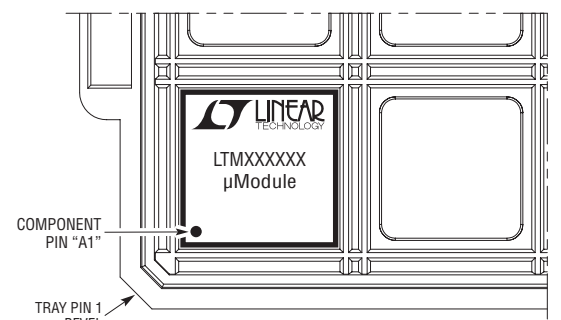


SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.12	3.32	3.52	
A1	0.40	0.50	0.60	BALL HT
A2	2.72	2.82	2.92	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D	15.0			
E	15.0			
e	1.0			
F	13.0			
G	13.0			
H1	0.27	0.32	0.37	SUBSTRATE THK
H2	2.45	2.50	2.55	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.25	
eee			0.10	

TOTAL NUMBER OF BALLS: 186

- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 - ALL DIMENSIONS ARE IN MILLIMETERS
 - CALLOUT 3 BALL DESIGNATION PER JEP95
 - CALLOUT 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 - PRIMARY DATUM -Z- IS SEATING PLANE
 - CALLOUT 6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION